



Embedded Systems Week

www.esweek.org

Sept. 30 – Oct. 5, 2018

Torino Incontra, Torino, Italy



"view of the city of Turin" (http://www.dianliwenmi.com/posting_3861909.html)

Call for Papers, Workshops, Tutorials

- CASES • CODES+ISSS • EMSOFT • IoT • Symposia • Workshops • Tutorials •

About Embedded Systems Week (ESWEEK)

Embedded Systems Week (ESWEEK) is the premier event covering all aspects of embedded systems and software. By bringing together three leading conferences (CASES, CODES+ISSS, EMSOFT), a special IoT Day, three symposia (ESTIMedia, RSP, NOCS), and hot-topic workshops and tutorials, ESWEEK presents attendees a wide range of topics unveiling the state of the art in embedded systems design and HW/SW architectures.

One Registration, three Conferences !

Registered attendees are entitled to attend sessions of all conferences CASES, CODES+ISSS, EMSOFT, and the IoT Day. Symposia, workshops and tutorials require separate registration.

Journal Track:

Abstract Submission: March 27, 2018
 Full Paper Submission: April 3, 2018 (firm)
 Notification of Acceptance: July 1, 2018

Work-in-Progress Track:

Paper Submission: May 30, 2018 (firm)
 Notification of Acceptance: July 1, 2018

Workshop Proposals: March 27, 2018

Tutorial Proposals: April 3, 2018



International Conference on Compilers, Architectures, and Synthesis for Embedded Systems

CASES is a premier forum where researchers, developers and practitioners exchange information on the latest advances in compilers and architectures for high-performance, low-power embedded systems. The conference has a long tradition of showcasing leading edge research in embedded processor, memory, interconnect, storage architectures and related compiler techniques targeting performance, power, predictability, security, reliability issues for both traditional and emerging application domains. In addition, we invite innovative papers that address design, synthesis, and optimization challenges in heterogeneous and accelerator-rich architectures.

CASES Program Chairs

Tulika Mitra, National University of Singapore, SG
 Akash Kumar, Technical University of Dresden, DE

Tutorials



International Conference on Embedded Software

The ACM SIGBED International Conference on Embedded Software (EMSOFT) brings together researchers and developers from academia, industry, and government to advance the science, engineering, and technology of embedded software development. Since 2001, EMSOFT has been the premier venue for cutting-edge research in the design and analysis of software that interacts with physical processes, with a long-standing tradition for results on cyber-physical systems, which compose computation, networking, and physical dynamics.

EMSOFT Program Chairs

Björn Brandenburg, MPI for Software Systems, DE
 Sriram Sankaranarayanan, University of Colorado Boulder, US

International Conference on Hardware/Software Codesign and System Synthesis



The International Conference on Hardware/Software Codesign and System Synthesis is the premier event in system-level design, modeling, analysis, and implementation of modern embedded and cyber-physical systems, from system-level specification and optimization down to system synthesis of multi-processor hardware/software implementations. The conference is a forum bringing together academic research and industrial practice for all aspects related to system-level and hardware/software co-design. High-quality original papers will be accepted for oral presentation followed by interactive poster sessions.

Workshops

CODES+ISSS Program Chairs

Aviral Shrivastava, Arizona State University, US
 Sudeep Pasricha, Colorado State University, US

Symposia

Keynotes



Internet-of-Things

IoT

The Internet of Things (IoT) promises to revolutionize fields ranging from health care to manufacturing to personal living by connecting the Internet to physical things. Embedded computing is central to the achievement of the IoT vision – advanced computation, communication, and storage must be delivered in a safe, secure, and reliable manner at extremely low energy levels. The IoT special day is devoted to research on advanced IoT systems. It will provide a forum for academia and industry to present and discuss innovative ideas and solutions related to all facets of internet-of-things. Submissions to the IoT day are done via the three conferences.

IoT Chair.

Chenyang Lu, Washington University in St. Louis, US

ESWEEK 2018 has a dual publication model with two tracks: Journal track papers will be published in IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, and Work-in-Progress track papers will be published in the ESWEEK Proceedings. <http://www.esweek.org/author-information>

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Paper Process

ESWeek 2018 continues a dual publication model comprising two tracks, namely the Journal track and the Work-in-Progress (WiP) track. Journal track papers, which are full-length (10-page) papers describing mature work, will be published in IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD). The WiP track papers, which are short (2-page) papers representing not-yet-mature but promising research work, will be published in the ESWEEK proceedings and will be listed as regular publications within the IEEE and/or ACM digital libraries. Authors of WiP papers have the opportunity to publish the extended final form of their work when it has matured in any conference or journal they prefer. Journal papers and WiP papers are mutually exclusive, i.e., a work can only be in submission in one of the two tracks. For more information, please refer to <http://www.esweek.org/author-information>.

Call for Workshops and Tutorials

Call for Workshop Proposals

ESWEEK 2018 will host several workshops on Oct. 4/5th and is soliciting proposals for new and recurring workshops. ESWEEK workshops are excellent opportunities to bring together researchers and practitioners from different communities to share their experiences in an interactive atmosphere, and to foster collaboration for new and innovative projects.

We invite you to submit workshop proposals on any topic related to the broad set of research, education, and application areas in embedded systems before the **deadline of March 27, 2018**.

Workshop Chair

Muhammad Shafique, Vienna University of Technology, AT

Call for Tutorial Proposals

ESWEEK 2018 is looking for high-quality, timely tutorials to enrich its technical program. Tutorials offer a unique opportunity where presenters can interact closely with attendees and attendees can gain in-depth knowledge on a specific topic. Tutorials on all topics related to embedded system design, analysis and development are welcome. ESWEEK 2018 tutorials will take place on Sept. 30th, and can be either be half day or full day, lecture style or hands on labs.

We invite you to submit tutorial proposals before the **deadline of April 3, 2018**.

Tutorials Chair

Andreas Gestlauer, University of Texas Austin, US

Sponsoring Societies:



ESWEEK 2018 General Chairs

- Soonhoi Ha, Seoul National University, KR
- Petru Eles, Linköping University, SE
- Lothar Thiele, Swiss Federal Institute of Technology, CH

ESWEEK Conference Program Chairs

CASES

- Tulika Mitra, National University of Singapore, SG
- Akash Kumar, Technical University of Dresden, DE

CODES+ISSS

- Aviral Shrivastava, Arizona State University, US
- Sudeep Pasricha, Colorado State University, US

EMSOFT

- Björn Brandenburg, MPI for Software Systems, DE
- Sriram Sankaranarayanan, Univ. of Colorado Boulder, US

ESWEEK Organizational Chairs

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- Enrico Bini, University of Torino, IT

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